



Appl. No. 09/768,845

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: HO et al.

Examiner: LUAN THAI

Art Unit: 2827

Title PACKAGING STRUCTURE OF IMAGE SENSOR AND
METHOD FOR PACKAGING THE SAME

To: THE ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Subject: RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated 10/23/2002, Applicant submits the
5 following amendments and remarks.

AMENDMENTS

IN THE CLAIMS:

Please amend claim 1 as follows:

10 Claim 1 has been amended as follows:

1. (Thrice Amended) A packaging structure of an image sensor, comprising:

a substrate including a plurality of straight metal sheets directly penetrating
through the substrate, glue for sealing the metal sheets after the metal sheets are
formed, a first surface having a periphery, and a second surface opposite to the
15 first surface, the metal sheets being exposed to the outside via the first surface and
the second surface to form first contacts and second contacts, respectively,
wherein the glue surrounds the plurality of straight metal sheets;

a projecting edge provided on the periphery of the first surface of the
substrate to form a concavity above the substrate, the projecting edge being
20 arranged on the glue;

an image sensing chip mounted on the glue of the substrate and within the